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# United States Patent

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[54] METHOD FOR MAKING A WAFER-PAIR  
HAVING SEALED CHAMBERS

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438/700; 438/703

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216/39, 56; 438/54, 456, 700, 703

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## [57] ABSTRACT

A method for fabricating a wafer-pair having at least one recess in one wafer and the recess formed into a chamber with the attaching of the other wafer which has a port plugged with a deposited layer on its external surface. The deposition of the layer may be performed in a very low pressure environment, thus assuring the same kind of environment in the sealed chamber. The chamber may enclose at least one device such as a thermoelectric sensor, bolometer, emitter or other kind of device. The wafer-pair typically will have numerous chambers, with devices, respectively, and may be divided into a multiplicity of chips.

24 Claims, 4 Drawing Sheets

